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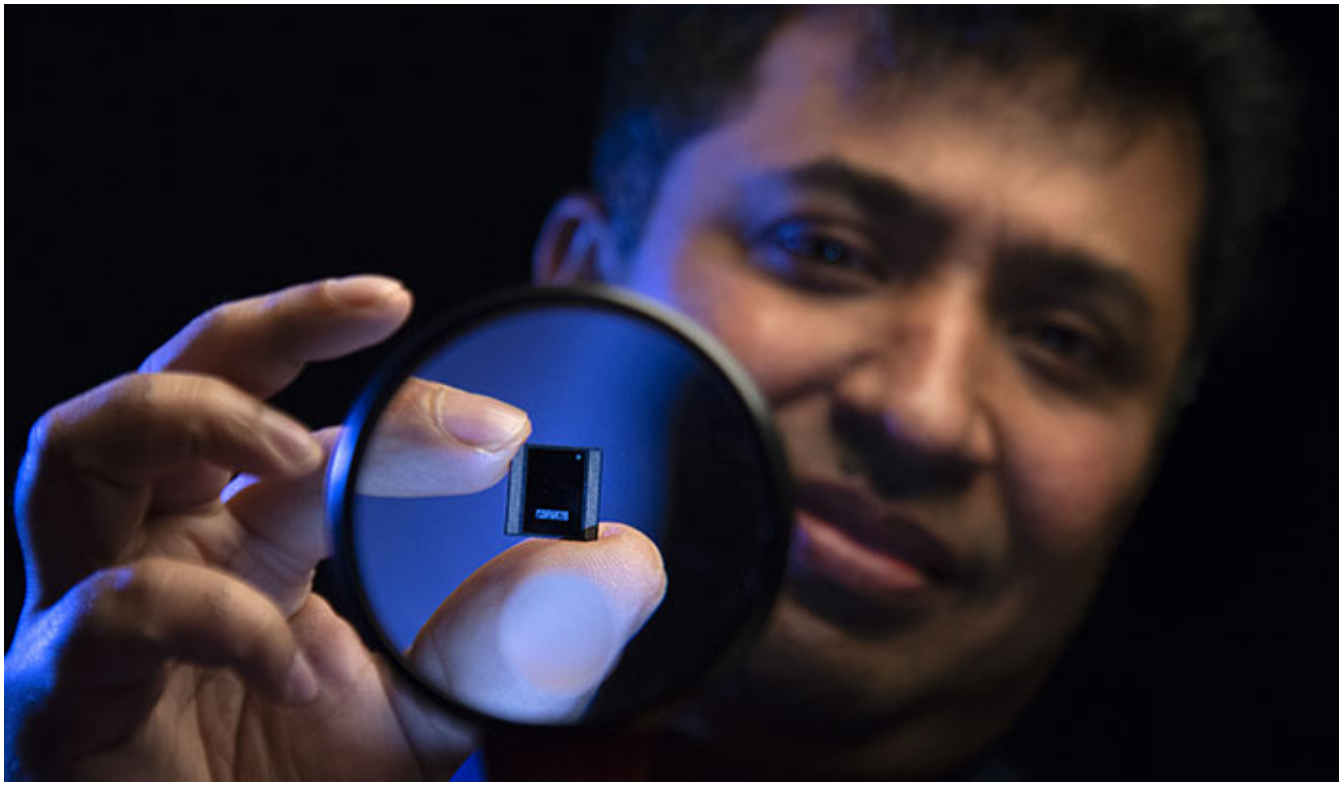
An Intel blog post details the manufacturing process behind Lakefield, an upcoming Core processor featuring "hybrid" technology-- specifically a means to mix power-efficient Tremont cores with a performance-scalable Sunny Cove core.



Dubbed Foveros, the process stacks components in three dimensions, making something of a silicon layer cake (if one just 1mm thick). Such packaging technology allows Chipzilla to "mix and match" technology IP blocks with various memory and I/O elements in a small physical package, allowing for "significantly reduced" board size.

In fact, the Lakefield package area measures 12 x 12 x 1mm, even as it mixes Tremor cores with the Sunny Cove core. The result, Intel claims, is a processor able to intelligently deliver productivity performance when required before switching to power-sipping efficiency when not needed in order to increase battery life.

Lakefield finds use in at least 3 upcoming devices-- the dual-screen Surface Neo, the Samsung Galaxy Book S thin-and-light laptop and the Lenovo ThinkPad X1 Fold foldable PC.

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